

Electronic Acknowledgement Receipt

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First Named Inventor:	Shih-Fang Chuang
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		TI-36243_1_111.pdf	7772	yes	4

	Multipart Description		
	Doc Desc	Start	End
	Amendment - After Non-Final Rejection	1	1
	Claims	2	3
	Applicant Arguments/Remarks Made in an Amendment	4	4
Warnings:			
Information:			
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